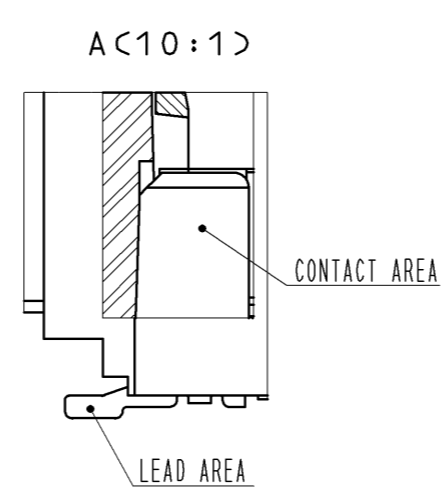
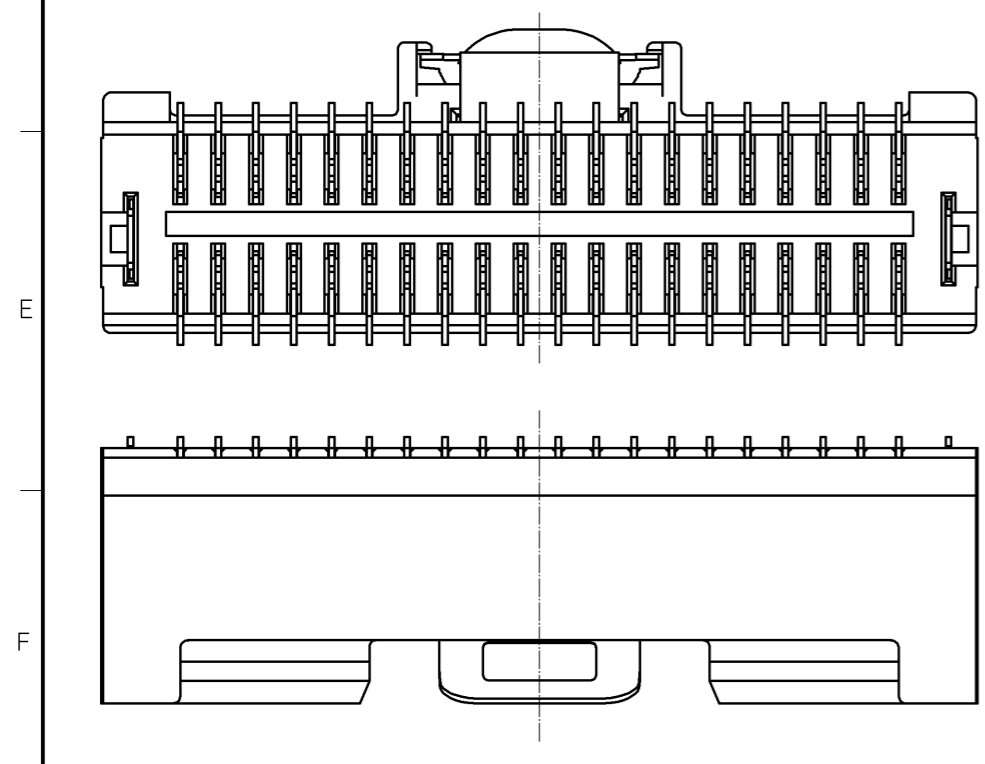
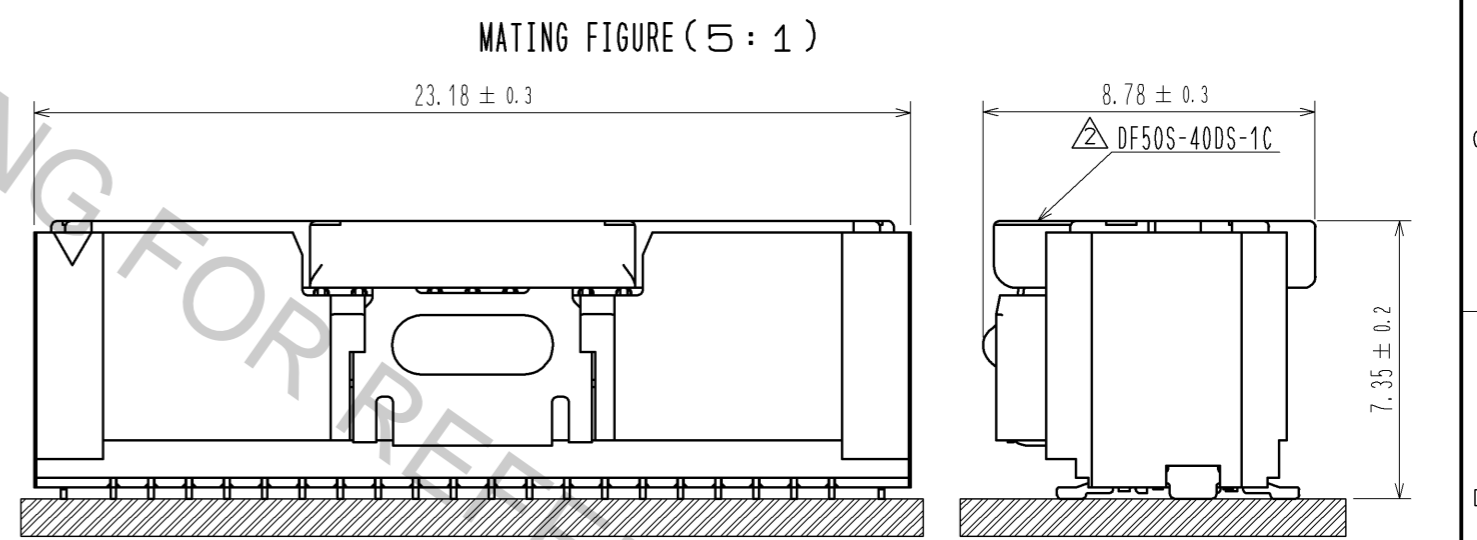
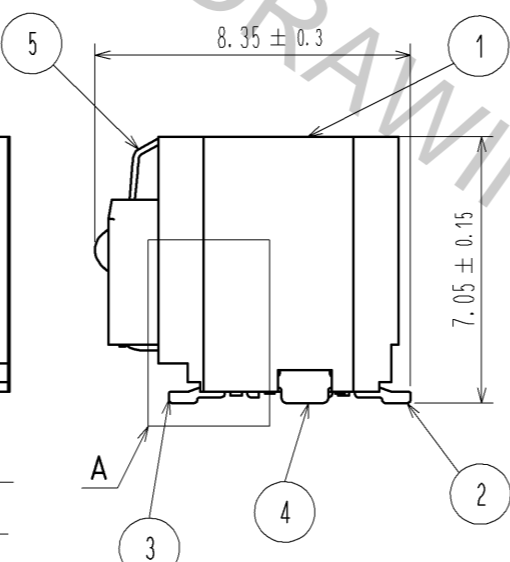
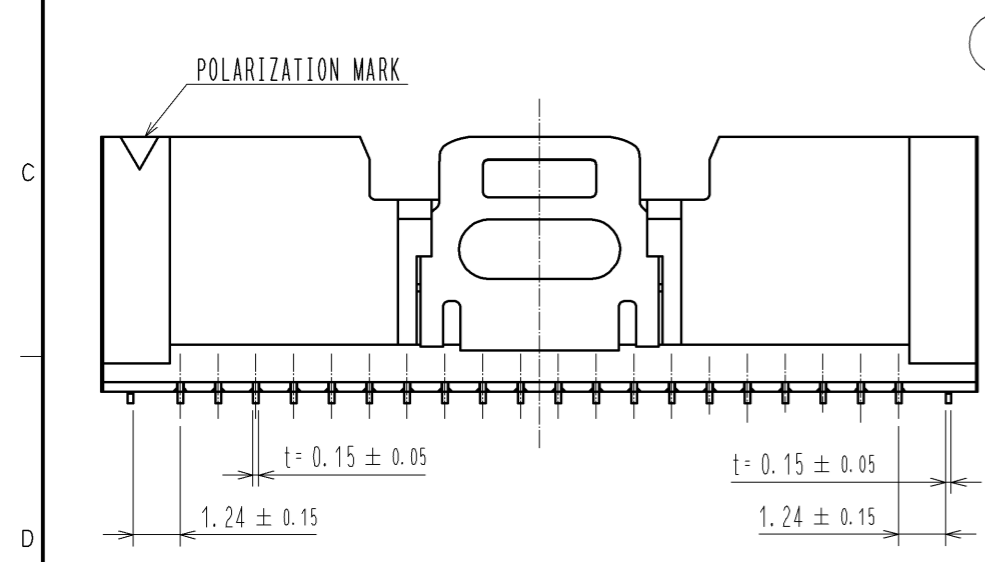
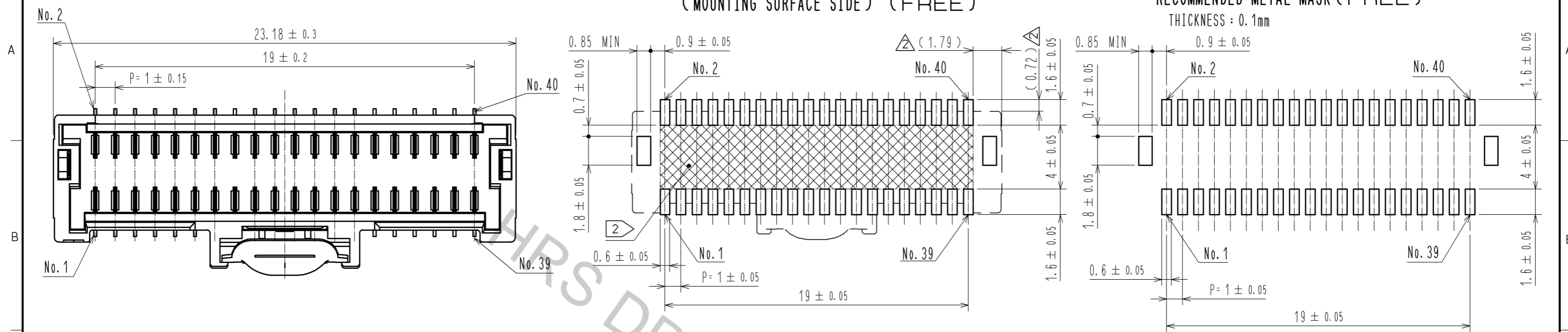


RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)

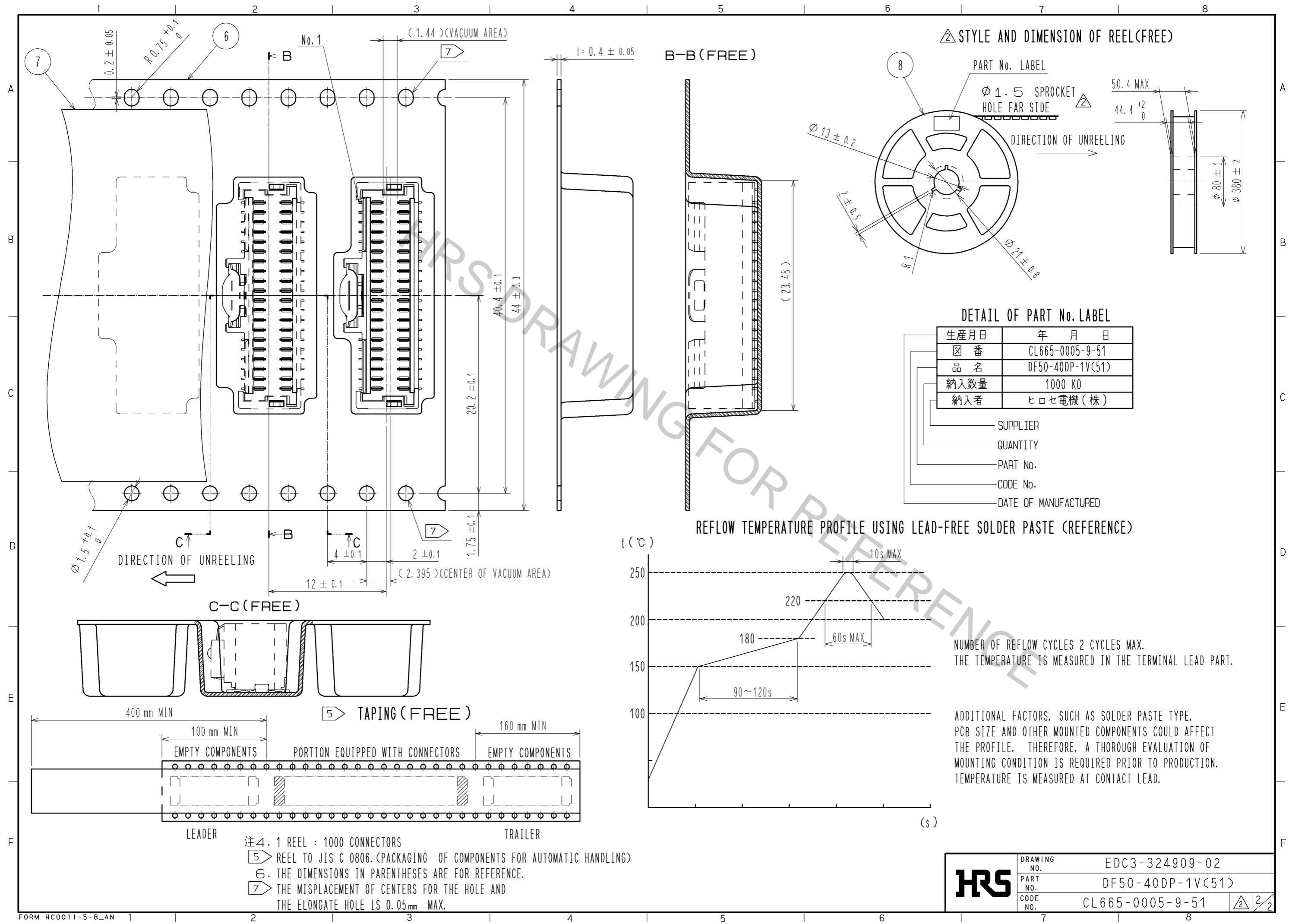
RECOMMENDED METAL MASK (FREE)

THICKNESS : 0.1mm



- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

3	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	8	PS	REEL. BLACK
			7	POLYESTER	CLEAR
2	BRASS	CONTACT AREA : Au PLATING 0.05 μm MIN LEAD AREA : Au PLATING 0.05 μm MIN UNDER PLATING : Ni PLATING 1 μm MIN	6	PS	CLEAR
			5	STAINLESS STEEL	—
1	LCP	BLACK, UL94V-0	4	BRASS	CONTACT AREA : Sn PLATING 1 μm MIN UNDER PLATING : Ni PLATING 0.5 μm MIN
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE FREE	COUNT 5	DESCRIPTION OF REVISIONS DIS-H-007735	
DESIGNED MI. SAKIMURA			CHECKED TS. KUMAZAWA		
DATE 13. 03. 22			DRAWING NO. EDC3-324909-02		
APPROVED : TS. SAKATA 10. 01. 18			PART NO. DF50-40DP-1V(51)		
CHECED : HK. UMEHARA 10. 01. 18			CODE NO. CL665-0005-9-51		
DESIGNED : TT. OHSAKO 10. 01. 18					
DRAWN : TT. OHSAKO 10. 01. 18					



HRS	DRAWING NO.	EDC3-324909-02
	PART NO.	DF50-40DP-1V(51)
	CODE NO.	CL665-0005-9-51
		2/2